

## ● USPQ-4B05 Power Dissipation

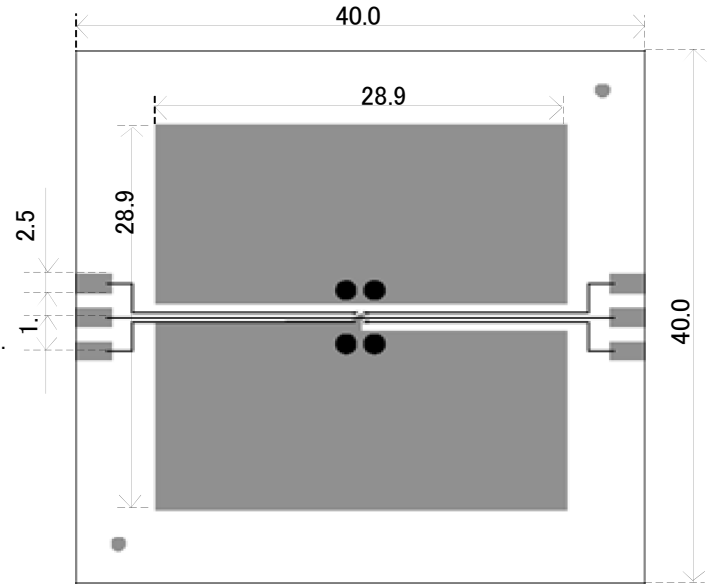
Power dissipation data for the USPQ-4B05 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as the reference data taken in the following condition.

### 1. Measurement Condition

Condition:	Mount on a board
Ambient:	Natural convection
Soldering:	Lead (Pb) free
Board:	Dimensions 40 x 40 mm (1600 mm <sup>2</sup> in one side) 4 Copper Layers Each layer is connected to the package heat-sink and terminal pin No.1. Each layer has approximately 800mm <sup>2</sup> copper area.
Material:	Glass Epoxy (FR-4)
Thickness:	1.6 mm
Through-hole:	4 x 0.8 Diameter



Evaluation Board (Unit: mm)

### 2. Power Dissipation vs. Ambient Temperature

Board Mount ( $T_j$  max = 125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	550	181.82
85	220	

